

directly or through one of the switching LSIs. This enables efficiency in module setup and the placement of elements in a small space. Refer to Fig. 10 and the paragraph bridging pages 17 and 18 of the present specification, for example.

On the other hand, Huang discloses patch areas that are provided for flexible interconnections between programmable logic components 212a or 212b, the Q-part 250 and the connector 220a, as explained at col. 13, line 29-33 of the reference. As shown in Figs. 3a, 3b, however, there is no direct connection of the FPGAs 330, even though the patch areas 340 are disclosed for providing flexible interconnections between the FPGAs. Accordingly, Huang does not anticipate the claimed invention of claims 1 and 13.

With respect to claim 16, the claim has been amended to include that each of the connectors is a stacking type connector. This provides a multiple stage module setup to be made available for promoting expansion of the logic scale and extensions in functionality. See page 14, lines 7-13 of the specification, for example. Huang does not disclose a comparable stacking type connector and therefore claim 16, as amended, is not anticipated by Huang.

Claim 22 has been amended to set forth that one edge of a flexible heat conduction sheet is attached to the radiation plates on the first side of the board on which to mount the plurality of integrated circuits and connectors, and another edge of the flexible heat conduction sheet is attached to the radiation plates on the second side of the board, wherein the opposite plane of the radiation plates on the first side of the board is capable of being provided with an integrated circuit mounted on another board. As claimed, two radiation plates are connected to each other via the flexible heat conduction sheet. In this way, one of the radiation plates is capable of being shared with two different boards. This provides efficient cooling for individual modules and multi-stage module setups. Francis, on the other hand, does not teach or disclose a multi-stage module setup. Accordingly, Francis does not suggest a radiation plate shared with two different boards and a radiation plate connected to another radiation plate via a flexible heat conduction sheet, and therefore the rejection under 35 U.S.C. 103(a) should be withdrawn.

Although the arguments presented herein are directed to the independent claims, the dependent claims set forth additional limitations that are not disclosed or suggested by the art of record. Further each of these claims includes the limitations of the base claim from which it depends, so none of these claims are disclosed or suggested by Huang or Francis for the foregoing reasons.

In view of the foregoing amendments and remarks, reconsideration and reexamination are respectfully requested.

Respectfully submitted,



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